

Amendments to the Claims:

The listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A system for integrating circuitry on an isolation layer, comprising:

- a plurality of isolation substrates, each isolation substrate having a circuit deposition region and a substrate-combining region;
- a plurality of circuits formed on the circuit deposition regions;
- a plurality of substrate-connecting elements formed to connect the substrate-combining regions; and
- a plurality of electrical connecting elements formed to electrically connect the circuits formed on the different circuit deposition regions, wherein the circuit deposition region contacts the substrate-combining region on different planes.

Claim 2 (original): The system as claimed in claim 1, wherein the substrate-connecting elements are formed by heat fusing or laser.

Claim 3 (original): The system as claimed in claim 1, wherein the electrical connecting elements are flex print cables or gold lines.

Claim 4 (original): The system as claimed in claim 1, wherein the electrical connecting elements are formed by laser fusing.

Claim 5 (original): The system as claimed in claim 1, wherein the materials of the isolation substrates are different.

Claim 6 (canceled)

Claim 7 (original): The system as claimed in claim 1, wherein the materials of the isolation substrates are plastic or glass.

Claim 8 (currently amended): A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate including a first circuit deposition region and a first substrate-combining region, and a second isolation substrate including a second circuit deposition region and a second substrate-combining region;

forming a first circuit and a second circuit respectively on the first circuit deposition region and the second circuit deposition region;

contacting the first substrate-combining region and the second substrate-combining region;

forming a plurality of substrate-connecting elements for connecting the first substrate-combining region to the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the first circuit and the second circuit.

Claim 9 (original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the substrate-connecting elements are formed by heat fusing or laser.

Claim 10 (original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the electrical connecting elements are flex print cables or gold lines.

Claim 11 (original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the electrical connecting elements are formed by laser fusing.

Claim 12 (original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the first circuit and the second circuit are packed by different packaging methods.

Claim 13 (original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the material of the first isolation substrate and the second isolation substrate is plastic.

Claim 14 (original): The method for integrating a system on an isolation layer as claimed in claim 8, wherein the material of the first isolation substrate and the second isolation substrate are glass.

Claim 15 (original): A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate and a second isolation substrate respectively including a first circuit deposition region and a second circuit deposition region;

forming a plurality of first circuits and a plurality of second circuits respectively on the first circuit deposition region and the second circuit deposition region;

cutting the first isolation substrate and the second isolation substrate, wherein the cut first isolation substrate comprises single first circuit and a first substrate-combining region, and the cut second isolation substrate comprises a single second circuit and a second substrate-combining region;

forming a plurality of substrate-connecting elements for connecting the cut first isolation substrate to the cut second isolation substrate, wherein the first substrate-combining region contacts the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the single first circuit and the single second circuit.

Claim 16 (original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the substrate-connecting elements are formed by heat fusing or laser.

Claim 17 (original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the electrical connecting elements are flex print cables or gold lines.

Claim 18 (original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the electrical connecting elements are formed by laser fusing.

Claim 19 (original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the material of the first isolation substrate is plastic.

Claim 20 (original): The method for integrating a system on an isolation layer as claimed in claim 15, wherein the material of the second isolation substrate is glass.

Claim 21 (new): A method for integrating a system on an isolation layer, comprising the following steps:

providing a first isolation substrate including a first circuit deposition region and a first substrate-combining region, and a second isolation substrate including a second circuit deposition region and a second substrate-combining region;

forming a first circuit and a second circuit respectively on the first circuit deposition region and the second circuit deposition region, wherein the first circuit and the second circuit are packed by different packaging methods;

forming a plurality of substrate-connecting elements for connecting the first substrate-combining region to the second substrate-combining region; and

forming a plurality of electrical connecting elements to electrically connect the first circuit and the second circuit.